

L Number	Hits	Search Text	DB	Time stamp
1	1328	chip adj inductor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/26 23:32
2	45	(chip adj inductor) and (metal\$4 adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/26 23:33
-	6	cyлинд\$6 and forming and (coil adj pattern) and (ferrite or ceramic) and powder and binder and square and temperature	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/26 21:11
-	252	chip adj inductor	USPAT	2003/01/26 21:11
-	35	(chip adj inductor) and цилинд\$6 and square	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/26 21:16
-	3	(chip adj inductor) and mold and metal and (ferrite or ceramic) and powder and pressure and temperature and spiral and (dip or plat\$3 or sputter) and laser and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/26 21:18
-	4	(chip adj inductor) and mold and metal and (ferrite or ceramic) and powder and pressure and temperature and (dip or plat\$3 or sputter) and laser and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/26 21:19
-	10	(chip adj inductor) and mold and metal and (ferrite or ceramic) and powder and pressure and temperature and (dip or plat\$3 or sputter) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/26 21:20
-	10	(chip adj inductor) and mold and metal and (ferrite or ceramic) and powder and temperature and (dip or plat\$3 or sputter) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/26 21:20